

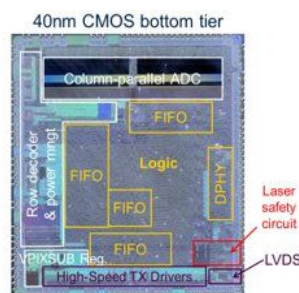
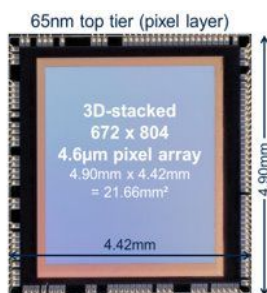
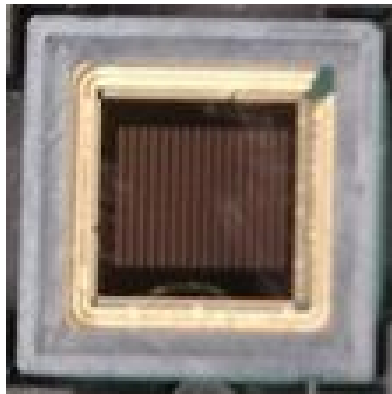


TECHNOLOGY FOR DEPTH MAP SENSORS

« SELLING » STATEMENT:

Fully European Differentiated Silicon Technology able to serve Consumer and Industrial 3D imagers products with high volume capacities.

Allowing greater ranges, faster readings, and enhanced accuracy to cope with new technology needs and markets (AR/VR, mobile, etc.)



KEY FEATURES

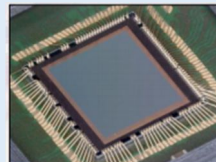
3D-SPAD: Aggressive performance target for high resolution imager achieved

3D40 (40nm) and now 3D28SPAD (28nm) processes will enable STMicroelectronics next generation devices to increase our market pervasion in 3D imaging.

Lock-in pixel technology: A fully new promoted product (S2)

Latest ST iToF test chip designed to allow characterization of lock-in pixel specific figures of merit

Such Test-chip made available along VIZTA is now available under ST VD55H1 Die level product !



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